



Fee

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re U.S. Patent Application of

TACHIBANA et. al.

Application Number: 10/701,499

Filed: November 6, 2003

**For: HEAT SPREADER AND SEMICONDUCTOR
DEVICE AND PACKAGE USING THE SAME**

Attorney Docket No. KOBE.0057

Art Unit 2814

**Examiner
Rao, Shrinivas H.**

**Honorable Assistant Commissioner
for Patents
Washington, D.C. 20231**

COVER LETTER

Sir:

The fee for submission of claims is calculated as shown below:

FOR	TOTAL WITH NEW CLAIMS ADDED	TOTAL CURRENTLY ON FILE	CLAIMS ALREADY PAID	RATE	CALCULATION
Total Claims	5	12	-XX (Over 20)	x \$50	0
Independent Claims	2	3	-XX (Over 3)	x \$200	0
MULTIPLE DEPENDENT CLAIM(S)				+ \$360	0
REDUCTION FOR FILING BY SMALL ENTITY (note 37 C.F.R. §§ 1.9, 1.27, 1.28).				x 1/2	
				TOTAL	0.00

In addition, the below-identified communications are submitted in the above-captioned application or proceeding:

<input checked="" type="checkbox"/> Response to Office Action (with Claim Amendments)	<input type="checkbox"/> Petition for Extension of Time
<input type="checkbox"/> Substitute Specification	<input type="checkbox"/> Terminal Disclaimer
<input type="checkbox"/> Preliminary Amendment	<input type="checkbox"/> Letter to Draftsperson
<input type="checkbox"/> Information Disclosure Statement	<input type="checkbox"/> Assignment
	<input type="checkbox"/> Other _____

[] Please charge my **Deposit Account Number** _____ in the amount of _____ to cover the fees for _____. A duplicate copy of this paper is enclosed.

[] A check in the amount of **\$0.00** to cover the _____ fee is enclosed.

[x] The Commissioner is hereby authorized to charge any additional fees associated with this communication, including fees under 37 C.F.R. § 1.16 and 1.17, or credit any overpayment to **Deposit Account Number 08-1480**.

Respectfully submitted,

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August 10, 2005



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**Honorable Assistant Commissioner
for Patents
Washington, D.C. 20231**

RESPONSE AND AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

This is in response to the office action dated May 24, 2005, in the above identified application, the period for response is set to expire on August 24, 2005. Please amend the above-referenced application as follows: